

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT4924061

<b>SUBMISSION TYPE:</b>	CORRECTIVE ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	Corrective Assignment to correct the ASSIGNEE'S NAME previously recorded on Reel 035762 Frame 0693. Assignor(s) hereby confirms the CORRECTION OF ASSIGNEE'S NAME ON THE CORRECTIVE ASSIGNMENT.

## CONVEYING PARTY DATA

Name	Execution Date
PEI-CHENG HSU	05/22/2015
CHIH-CHENG LIN	05/22/2015
HSIN-CHANG LEE	05/22/2015
TA-CHENG LIEN	05/22/2015
ANTHONY YEN	05/22/2015

## RECEIVING PARTY DATA

<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
<b>Street Address:</b>	NO. 8, LI-HSIN RD. 6
<b>Internal Address:</b>	SCIENCE-BASED INDUSTRIAL PARK
<b>City:</b>	HSIN-CHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14726317

## CORRESPONDENCE DATA

**Fax Number:** (214)200-0853  
*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

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**Email:** ipdocketing@haynesboone.com  
**Correspondent Name:** HAYNES AND BOONE, LLP IP SECTION  
**Address Line 1:** 2323 VICTORY AVENUE  
**Address Line 2:** SUITE 700  
**Address Line 4:** DALLAS, TEXAS 75219

<b>ATTORNEY DOCKET NUMBER:</b>	20150072/24061.3106US01
<b>NAME OF SUBMITTER:</b>	JANIE MARTINEZ-HOLM
<b>SIGNATURE:</b>	/Janie Martinez-Holm/

PATENT

<b>DATE SIGNED:</b>	04/19/2018
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**Total Attachments: 6**

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<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT3377809

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
PEI-CHENG HSU	05/22/2015
CHIH-CHENG LIN	05/22/2015
HSIN-CHANG LEE	05/22/2015
TA-CHENG LIEN	05/22/2015
ANTHONY YEN	05/22/2015
<b>RECEIVING PARTY DATA</b>	
<u>MANUFACTURING</u>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
<b>Street Address:</b>	NO. 8, LI-HSIN RD. 6
<b>Internal Address:</b>	SCIENCE-BASED INDUSTRIAL PARK
<b>City:</b>	HSIN-CHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14726317
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	214-651-5000
<b>Email:</b>	ipdocketing@haynesboone.com
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<b>Address Line 2:</b>	SUITE 700
<b>Address Line 4:</b>	DALLAS, TEXAS 75219
<b>ATTORNEY DOCKET NUMBER:</b>	20150072/24061.3106US01
<b>NAME OF SUBMITTER:</b>	JANIE MARTINEZ-HOLM
<b>SIGNATURE:</b>	/Janie Martinez-Holm/
<b>DATE SIGNED:</b>	06/02/2015

**ASSIGNMENT**

WHEREAS, we,

- (1) Pei-Cheng Hsu of No. 23, Alley 12, Lane 63, Wu-Cheng Street Taipei, Taiwan, R.O.C.
- (2) Chih-Cheng Lin of 119 Dalian St. Sanmin Dist., Kaohsiung, 80757, Taiwan, R.O.C.
- (3) Hsin-Chang Lee of 3F., No. 26, Ln. 394, Xianzheng 2<sup>nd</sup> Rd., Zhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (4) Ta-Cheng Lien of No. 187, Wunchang St., Cyonglin Township, Hsinchu County, 307, Taiwan, R.O.C.
- (5) Anthony Yen of 20F-9, 188 Guanxin Road, Hinchu 300, Taiwan, R.O.C.

have invented certain improvements in

**PELLICLE ASSEMBLY AND FABRICATION METHODS THEREOF**

for which we have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and  
           filed on                            and assigned application number                           ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration; the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Pei-Cheng Hsu

Residence Address: No. 23, Alley 12, Lane 63, Wu-Cheng Street  
Taipei, Taiwan, R.O.C.

Dated: 2015 / 5 / 22

Pei Cheng Hsu  
Inventor Signature

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Inventor Name: Chih-Cheng Lin

Residence Address: 119 Dalian St. Sanmin Dist.,  
Kaohsiung, Taiwan, 80757, R.O.C.

Dated: 5/22, 2015

Chihcheng Lin  
Inventor Signature

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Inventor Name: Hsin-Chang Lee

Residence Address: 3F., No. 26, Ln. 394, Xianzheng 2nd Rd., Zhubei City,  
Hsinchu County 302, Taiwan, R.O.C.

Dated: 2015 / 5 / 22

Hsin-Chang Lee  
Inventor Signature

Docket No.: P20150072US01 / 24061.3106US01  
Customer No.: 000042717

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Inventor Name: Ta-Cheng Lien

Residence Address: No. 187, Wunchang St., Cyonglin Township,  
Hsinchu County, 307, Taiwan, R.O.C.

Dated: 2015 5 22

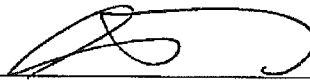
Ta Cheng Lien  
Inventor Signature

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Inventor Name: Anthony Yen

Residence Address: 20F-9, 188 Guanxin Road, Hinchu 300, Taiwan, R.O.C.

Dated: 5/22/15

  
Inventor Signature